

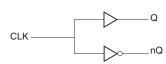
#### GENERAL DESCRIPTION

The 8302I-01 is a low skew, 1-to-2 LVCMOS/LVTTL Fanout Buffer w/Complementary Output. The 8302I-01 has a single ended clock input. The single ended clock input accepts LVCMOS or LVTTL input levels. The 8302I-01 is characterized at full 3.3V for input  $\rm V_{\rm DD},$  and mixed 3.3V and 2.5V for output operating supply modes (V<sub>DDO</sub>). Guaranteed output and partto-part skew characteristics make the 8302I-01 ideal for clock distribution applications demanding well defined performance and repeatability.

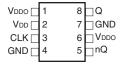
#### **F**EATURES

- · Complementary LVCMOS / LVTTL output
- LVCMOS / LVTTL clock input accepts LVCMOS or LVTTL input levels
- Maximum output frequency: 250MHz
- · Output skew: 165ps (maximum)
- Part-to-part skew: 800ps (maximum)
- Small 8 lead SOIC package saves board space
- Full 3.3V or 3.3V core/2.5V output supply modes
- -40°C to 85°C ambient operating temperature
- · Available in lead-free compliant package

## **BLOCK DIAGRAM**



### PIN ASSIGNMENT



8302I-01 8-Lead SOIC 3.8mm x 4.8mm, x 1.47mm package body M Package Top View



TABLE 1. PIN DESCRIPTIONS

Number	Name	Туре		Description
1, 6	$V_{\scriptscriptstyle DDO}$	Power		Output supply pins.
2	$V_{_{ m DD}}$	Power		Power supply pin.
3	CLK	Input Pulldown		LVCMOS / LVTTL clock input.
4,7	GND	Power		Power supply ground.
5	nQ	Output		Complementary clock output. LVCMOS / LVTTL interface levels.
8	Q	Output		Clock output. LVCMOS / LVTTL interface levels.

NOTE: Pulldown refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

Table 2. Pin Characteristics

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C <sub>IN</sub>	Input Capacitance			4		pF
C <sub>PD</sub>	Power Dissipation Capacitance (per output)	$V_{DD}, V_{DDO} = 3.465V$		22		pF
		$V_{DD} = 3.465V, V_{DDO} = 2.625V$		16		pF
R <sub>PULLDOWN</sub>	Input Pulldown Resistor			51		kΩ
R <sub>OUT</sub>	Output Impedance		5	7	12	Ω



#### **ABSOLUTE MAXIMUM RATINGS**

Supply Voltage,  $V_{DD}$  4.6V

Inputs,  $V_I$  -0.5 V to  $V_{DD}$  + 0.5 V

Outputs,  $V_{O}$  -0.5V to  $V_{DDO}$  + 0.5V

Package Thermal Impedance, θ<sub>JA</sub> 112.7°C/W (0 lfpm)

Storage Temperature, T<sub>STG</sub> -65°C to 150°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Table 3A. Power Supply DC Characteristics,  $V_{DD} = 3.3V \pm 5\%$ ,  $V_{DDO} = 3.3V \pm 5\%$  or  $2.5V \pm 5\%$ , Ta = -40°C to  $85^{\circ}$ C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V <sub>DD</sub>	Power Supply Voltage		3.135	3.3	3.465	V
V <sub>DDO</sub>	Output Power Supply Voltage		3.135	3.3	3.465	V
			2.375	2.5	2.625	V
I <sub>DD</sub>	Power Supply Current				13	mA
I <sub>DDO</sub>	Output Supply Current				4	mA

 $\textbf{TABLE 3B. LVCMOS / LVTTL DC Characteristics, V}_{DD} = 3.3 \text{V} \pm 5\%, \text{V}_{DDO} = 3.3 \text{V} \pm 5\% \text{ or } 2.5 \text{V} \pm 5\%, \text{Ta} = -40 ^{\circ}\text{C} \text{ to } 85 ^{\circ}\text{C}$ 

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
V <sub>IH</sub>	Input High Voltage			2		V <sub>DD</sub> + 0.3	V
V <sub>IL</sub>	Input Low Voltage			-0.3		0.8	V
I <sub>IH</sub>	Input High Current	CLK	$V_{DD} = V_{IN} = 3.465V$			150	μΑ
I	Input Low Current	CLK	$V_{DD} = 3.465V, V_{IN} = 0V$	-5			μΑ
	Output High Voltage		$V_{DDO} = 3.465, 50\Omega \text{ to } V_{DDO}/2$	2.6			V
<b>.</b> ,			V <sub>DDO</sub> = 3.465, I <sub>OH</sub> = -100μA	2.9			V
V <sub>OH</sub>			$V_{DDO} = 2.625, 50\Omega \text{ to } V_{DDO}/2$	1.8			V
			$V_{DDO} = 2.625, I_{OH} = -100\mu A$	2.2			V
			$V_{DDO} = 3.465, 50\Omega \text{ to } V_{DDO}/2$			0.5	V
V <sub>OL</sub>	Outrout Low Valtage		$V_{DDO} = 3.465, I_{OL} = 100 \mu A$			0.2	V
	Output Low Voltage		$V_{DDO} = 2.625, 50\Omega \text{ to } V_{DDO}/2$			0.5	V
			$V_{DDO} = 2.625, I_{OL} = 100 \mu A$			0.2	V



Table 4A. AC Characteristics,  $V_{DD} = V_{DDO} = 3.3V \pm 5\%$ ,  $T_A = -40$ °C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f <sub>MAX</sub>	Output Frequency				250	MHz
tp <sub>LH</sub>	Propagation Delay, Low-to-High; NOTE 1		1.8		2.7	ns
tsk(o)	Output Skew; NOTE 2, 4				165	ps
tsk(pp)	Part-to-Part Skew; NOTE 3, 4				800	ps
$t_R / t_F$	Output Rise/Fall Time	20% to 80%	300		800	ps
odo	Output Duty Cycle	<i>f</i> ≤ 133MHz	45		55	%
odc	Output Duty Cycle	133MHz < <i>f</i> ≤ 250MHz	40		60	%

NOTE 1: Measured from  $V_{DD}/2$  of the input to  $V_{DDO}/2$  of the output.

NOTE 2: Defined as skew between outputs at the same supply voltage and with equal load conditions.

Measured at V<sub>DDO</sub>/2.

NOTE 3: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured

NOTE 4: This parameter is defined in accordance with JEDEC Standard 65.

Table 4B. AC Characteristics,  $V_{DD} = 3.3V \pm 5\%$ ,  $V_{DDO} = 2.5V \pm 5\%$ , Ta = -40°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f <sub>MAX</sub>	Output Frequency				250	MHz
tp <sub>LH</sub>	Propagation Delay, Low-to-High; NOTE 1		1.9		2.9	ns
tsk(o)	Output Skew; NOTE 2, 4				250	ps
tsk(pp)	Part-to-Part Skew; NOTE 3, 4				900	ps
$t_R / t_F$	Output Rise/Fall Time	20% to 80%	100		850	ps
odc	Output Duty Cycle	<i>f</i> ≤ 133MHz	45		55	%
louc	Output Duty Cycle	133MHz < <i>f</i> ≤ 250MHz	40		60	%

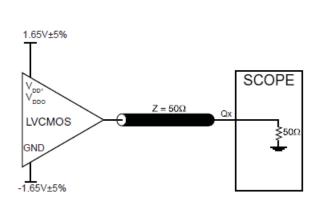
NOTE 1: Measured from  $V_{DD}/2$  of the input to  $V_{DDO}/2$  of the output. NOTE 2: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at V<sub>DDO</sub>/2.

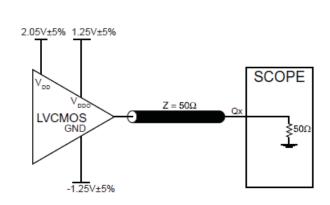
NOTE 3: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured

NOTE 4: This parameter is defined in accordance with JEDEC Standard 65.



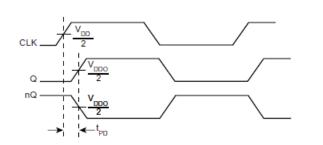
# PARAMETER MEASUREMENT INFORMATION

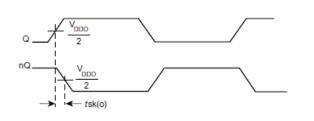




#### 3.3V CORE/3.3V OUTPUT LOAD AC TEST CIRCUIT

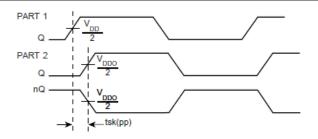


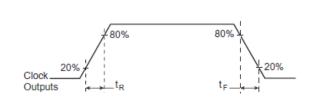




#### PROPAGATION DELAY

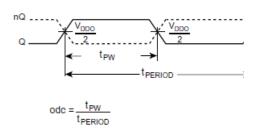
OUTPUT SKEW





#### PART-TO-PART SKEW

OUTPUT RISE/FALL TIME



#### OUTPUT DUTY CYCLE/PULSE WIDTH/PERIOD



## RELIABILITY INFORMATION

## Table 5. $\theta_{\rm JA}{\rm vs.}$ Air Flow Table for 8 Lead SOIC

### θJA by Velocity (Linear Feet per Minute)

O200500Single-Layer PCB, JEDEC Standard Test Boards153.3°C/W128.5°C/W115.5°C/WMulti-Layer PCB, JEDEC Standard Test Boards112.7°C/W103.3°C/W97.1°C/W

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

#### TRANSISTOR COUNT

The transistor count for 8302I-01 is: 322



#### PACKAGE OUTLINE - SUFFIX M FOR 8 LEAD SOIC

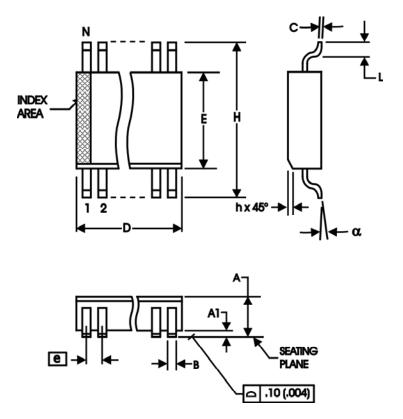


TABLE 6. PACKAGE DIMENSIONS

SYMBOL	Millin	neters
STWBOL	MINIMUN	MAXIMUM
N		8
Α	1.35	1.75
A1	0.10	0.25
В	0.33	0.51
С	0.19	0.25
D	4.80	5.00
E	3.80	4.00
е	1.27 BASIC	
Н	5.80	6.20
h	0.25	0.50
L	0.40	1.27
α	0°	8°

Reference Document: JEDEC Publication 95, MS-012



#### Table 7. Ordering Information

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
83054AGI-01LF	054Al01L	16 lead "Lead Free" TSSOP	Tray	-40°C to +85°C
83054AGI-01LFT	054AI01L	16 lead "Lead Free" TSSOP	Tape and Reel	-40°C to +85°C



	REVISION HISTORY SHEET					
Rev	Table	Page	Description of Change	Date		
А	Т7	8 10	Updated datasheet's header/footer with IDT from ICS. Removed ICS prefix from Part/Order Number column. Added Contact Page.	7/29/10		
А	T7	1 8	Features section - removed reference to leaded package.  Ordering Information - removed quantity from tape and reel. Deleted LF note below table.  Updated header and footer.	3/9/16		





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